

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	18DEC18	J.VIERNES
B	AS PER ECR-086562	07MAY19	J.VIERNES

**SPECIFICATIONS:**

**ROHS COMPLIANCE NOTE;** HOMOGENOUS MATERIALS IN THIS BOARD SHALL BE COMPLIANT THE EU RoHS DIRECTIVE 2002/95/EC

**MATERIALS;** ALL LAMINATES AND BONDING MATERIALS SHOULD BE SELECTED FROM IPC-4101 OR IPC-4103, MINIMUM T<sub>g</sub>>170degC, T<sub>d</sub>>300degC, U.L. RATING OF 94 V-0

**MATERIAL FAMILY;** ISOLA 370HR

**CLADDING;** EXTERNAL LAYERS 2 OZ. COPPER AFTER PLATING.  
INTERNAL SIGNAL LAYERS .5 OZ. COPPER.  
INTERNAL PLANE LAYERS 1 OZ. COPPER.

NOTE: IF THE LAYER STACKUP CONFLICTS WITH THE ABOVE CLADDING SPECIFICATIONS THEN THE LAYER STACKUP SHALL TAKE PRECEDENCE.

**SOLDER MASK;** SHALL BE LIQUID PHOTOIMAGEABLE (LPI) APPLIED ON BOTH SIDES OVER BARE COPPER OR GOLD AND SHALL MEET IPC-SM-840 (LATEST REV.) CLASS 3. COLOR GREEN.

**SILK SCREEN;** SHALL BE PERMANENT NON-CONDUCTIVE EPOXY INK. COLOR: WHITE  
SYNTHETIC INKJET PRINTING ALLOWED FOR DENSE BOARDS, COLOR: WHITE

**SURFACE FINISH;** ENIG (ELECTROLESS NICKEL/IMMERSION GOLD) PER IPC-4552 LATEST REVISION

**INTENTIONAL SHORTS;** IF SUPPLIED DATA INCLUDES A FILE "READ\_ME.2", THEN INTENTIONAL NET SHORTS EXIST. CUSTOMER REVIEW AND APPROVAL IS REQUIRED IF SUPPLIED DATA REPORTS ANY CONDITION THAT DOES NOT MATCH "READ\_ME.2" FILE PROVIDED.

**TEST REQUIREMENTS;** 100% NETLIST ELECTRICAL VERIFICATION USING CUSTOMER SUPPLIED IPC-D-356 NETLIST FOR OPENS AND SHORTS WHEN "GERBER DATA" IS PROVIDED. THIS VERIFICATION ALSO REQUIRED FOR "ODB++" DATA PER EMBEDDED NETLIST.

**REQUIREMENTS:**

- REFER TO IPC-6010 SERIES (LATEST REV.), CLASS 2 FOR FABRICATION UNLESS OTHERWISE SPECIFIED.
- ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00115, (LATEST REVISION.)
- MODIFICATIONS TO THE ARTWORK ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.
- HOLE PATTERN TOLERANCES FOR UNDIMENSIONED HOLES SHALL BE A DIAMETER OF 0.005 INCHES FROM THEIR TRUE POSITION.
- PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN 0.001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY CROSS SECTION.
- HOLE DIAMETERS APPLY AFTER PLATING.
- FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE NOMINAL INDICATED ON THE MASTER PATTERN, BY MORE THAN THE CONDUCTOR THICKNESS.
- MINIMUM DESIGN LINE WIDTH IS .008 INCH.
- MINIMUM DESIGN SPACING IS .007 INCH.
- ~~NON FUNCTIONAL PAD REMOVAL FROM INNER SIGNAL LAYERS MAY BE PERFORMED AFTER CUSTOMER APPROVAL.~~
- IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN ANNULAR RING REQUIREMENT, MFGR. MAY REQUEST APPROVAL TO TEAR DROP PADS TO MAINTAIN ANNULAR RING. (AT PAD TO TRACE INTERSECTION ONLY AND ELECTRICAL INTEGRITY MUST BE MAINTAINED.)
- THIEVING MAY BE ADDED TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN ONLY AFTER REVIEW AND APPROVAL FROM THE CUSTOMER:
  - A. THIEVING TO CARD EDGE, FIDUCIALS, NON-PLATED THROUGH HOLES, ALL OTHER FEATURES TO BE 0.200 INCH MINIMUM.
  - B. THERE SHALL BE NO THIEVING IN ANY AREAS FREE OF SOLDER MASK OR INTERNAL COPPER PLANES.
- MFGR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE IN A CLEAR AREA UNLESS OTHERWISE INDICATED;
  - A. U.L. CODE-FLAMMABILITY RATING
  - B. DATE CODE (STAMP).
  - C. LOT NUMBER
  - D. MFGR LOGO
  - E. SUCCESSFUL ELECTRICAL TEST.
- REPAIRS PER IPC-7711/21 (LATEST REV.) ARE ALLOWED. REPAIRS ARE NOT ALLOWED IN ANY AREA DEFINED ON GOLD\_PRM AND/OR GOLD\_SEC ARTWORK LAYERS WHEN PROVIDED IN GERBER OR ODB++ DATA.
- THRU VIAS TO BE FILLED WITH SOLDERMASK.

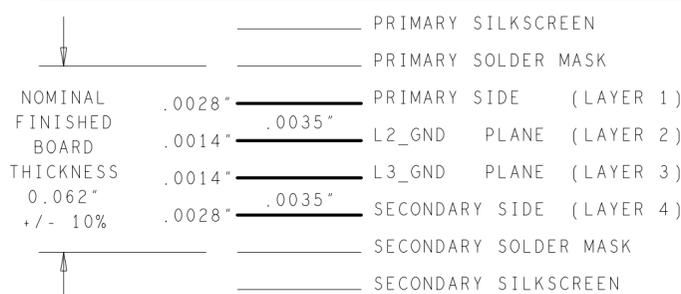
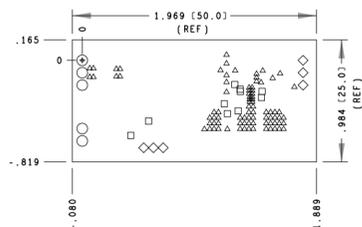
HOLE TOLERANCE

UNLESS SPECIFIED  
PLATED: +/- 3 MILS

FINISHED HOLES IN MILS				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
□	6.0	PLATED	10	SEE FAB NOTE 15
△	10.0	PLATED	83	SEE FAB NOTE 15
◇	40.0	PLATED	6	
○	45.0	PLATED	5	

DIA MAX  
DIA MAX

4 LAYER STACKUP



EVALUATION BOARD

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES		APPROVAL	DATE	ANALOG DEVICES		
TOLERANCES		TEMPLATE ENGINEER	N/A	WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887		
DECIMALS FRACTIONS ANGLES		HARDWARE SERVICES	N/A			
.XX -.010 --1/32 --2		HARDWARE SYSTEMS	N/A	TITLE FABRICATION SCP-LT3094 EVALZ		
.XXX -.005		N/A	N/A			
.XXXX -.0050		HARDWARE RELEASE	18DEC18	SIZE FSCM NO DRAWING NUMBER REV C 24355 09-051372 B		
MATERIAL		TEST ENGINEER	N/A			
FINISH		DESIGNER	18DEC18	SCALE 1/1 SHEET 1 OF 1		
DO NOT SCALE DWG		PTD ENGINEER	18DEC18			
		CHECKER	18DEC18			